

ABSTRAQCT OF THE DISCLOSURE

A semiconductor device includes semiconductor chips, a first conductive pattern, an external terminal and an encapsulating resin. Each of the semiconductor chips has a front side formed with integrated circuits and a back side. The semiconductor chips are stacked each other. The first conductive pattern electrically connects the integrated circuits. The external terminal is electrically connected to the first conductive pattern. The encapsulating resin encapsulates the semiconductor chips and the first conductive pattern.